



Micro Modular System

beyond AUTOMATION

WI300

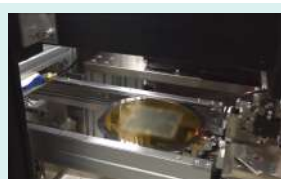
Fully Auto Wafer Inspection

WI 300 Wafer Inspection Machine is designed to deliver utmost flexibility to support top vision inspection for fabricated components on wafer such as lens, LED & IC packages from 4" tiles to 6" wafer.

With unique blend of flexibility and high performance, it makes an ideal inspection solution for automation industry.



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Machine Features



- **High Resoluton Camera**
Selection from 5MP to 65MP mono/color camera imaging technology
- **Wafer Die and Wire Bond Inspection**
Cosmetic and Wire Bond Checking
- **Auto Alignment Function**
2D decoding & Position Recognize (PR) vision
- **Real Time Wafer Map Display**
All inspection information such as mapping map, defect region inspection results is visualized for easy reading
- **Support Common Wafer Map Output Format**
STIF files
- **Minimum Defect Size**
5 μm x 5 μm
- **Confocal Displacement Sensor**
For warpage detection. Height compensation up to 2mm
- **Multiple Unit Inspection in Single Grab**

Inspection Criteria



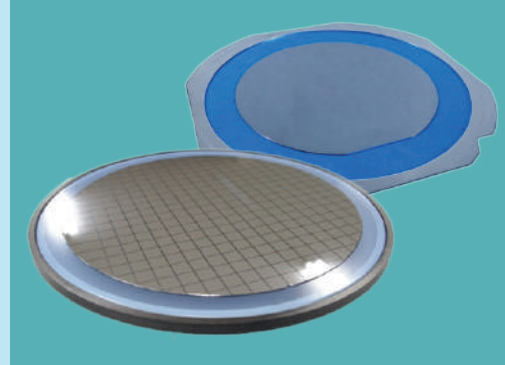
Type	
Wire Short	Double-Bond
Wire Broken	Lifted Wire
Wire Sagging	Lifted Ball
Wire Sweeping	Ball Dimension
Torn Bond	Particle on Die
Wire Missing	Die Offset
Epoxy Overflow	Lifted Stitch
Lead Bent	

Machine Specification

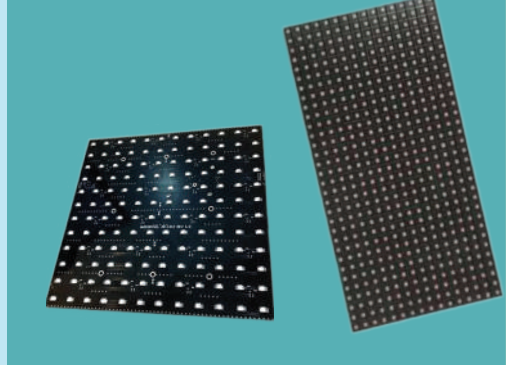


Product	4" – 6" wafer	
Specifications	Input:	Tiles, Wafer, Wafer rings
	Output:	Tiles, Wafer, Wafer rings
UPH	10K (single grab), 20K (multiple grab)	
Vision Inspection	Wire Bond and Cosmetic	
Inspection Area	6" x 6"	
Footprint	1250mm(W) x 2400mm(L) x 2050mm(H)	
Warranty	1 year limited excluding wear and tear parts	

Applicable Products



Wafer Ring
(4" - 6")



PCBA
Tiles

Other Products



SLD 001
Laser Diode
Tester



AT 100
COB LED
Test Machine



EOL Tester
Automotive
EOL Machine



RT 800
Reliability
Test System